

Features

- No Contact Sensing
- 5mm gap
- 0.5mm aperture
- Locating Pins
- PCB mount
- RoHS compliance

Description

The PIT5005T-02 consists of an infrared light emitting diode coupled to a NPN silicon phototransistor pack- aged into an injection molded housing. The housing is designed for wide-gap non-contact sensing.

Package Outline



Schematic



Absolute Maximum Rating at 25°C

Symbol	Parameters	Ratings	Units
Topr	Operating Temperature	-40 ~ +100	°C
T _{STG}	Storage Temperature	-55 ~ +100	°C
T _{SOL-I}	Soldering Temperature (Solder Iron) (2,3,4,5)	240 ~ 5 Sec	°C
T _{SOL-F}	Soldering Temperature (Solder Flow) (2,3,4,5)	260 ~ 10 Sec	°C
Emitter	•		
I _F	Continuous Forward Current	60	mA
V_R	Reverse Voltage	6	V
P _D	Power Dissipation ⁽¹⁾	150	mW
Detector			
V _{CEO}	Collector-Emitter Voltage	30	V
V _{ECO}	Emitter-Collector Voltage	4.5	V
I _C	Collector Current	20	mA
P _D	Power Dissipation ⁽¹⁾	100 mW	

Notes:

- 1 : Derate power dissipation linearly, on each component, 1.67 mW/ $^{\circ}$ C above 25 $^{\circ}$ C.
- 2: RMA Flux is recommended.
- 3: Methanol or isopropyl alcohols are recommended as cleaning agents.
- 4 : Soldering iron tip 1.6mm from housing.
- 5 : As long as leads are not under stress or spring tension

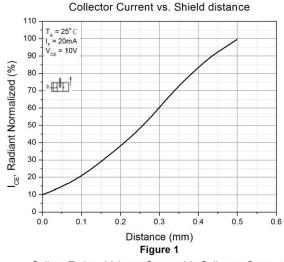


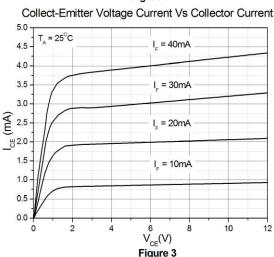
Electro-Optical Characteristics TA = 25°C (unless otherwise specified)

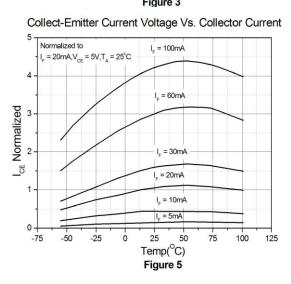
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units		
Emitter	Emitter							
VF	Forward Voltage	I _F =20mA	-	1.2	1.5	V		
I _R	Reverse Current	V _R =4V	-	-	10	μA		
λ _P	Peak Emissions Wavelength	I _F =20mA	-	940	-	пт		
Detector								
ID	Dark Current	V _{CE} =10V ; I _F =0mA	-	-	200	пА		
Coupled	Coupled							
I _{C(ON)}	Collector Current	IF=20mA; VCE =10V	0.5	-	14	mA		
VCE(SAT)	Collector - Emitter Saturation	IF 20m A IC 0.4m A	-	-	0.4	V		
	Voltage	IF=20mA; IC=0.1mA						
Tr	Rise Time	V_{CC} =5 V ; R_L =100 Ω ;	-	4	-	μs		
Tf	Fall Time	I _C =5mA	-	4	-	μs		

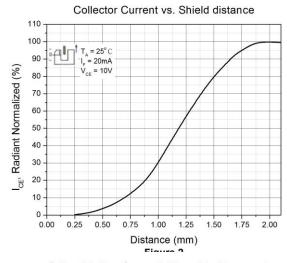


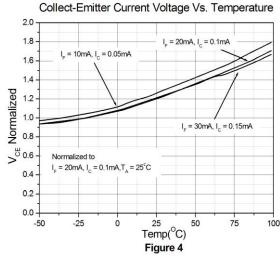
Typical Characteristic Curves

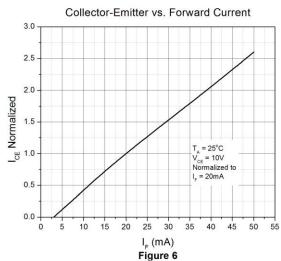






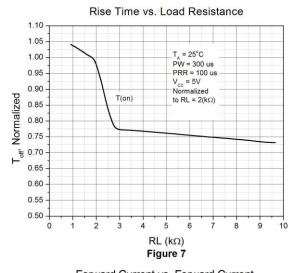


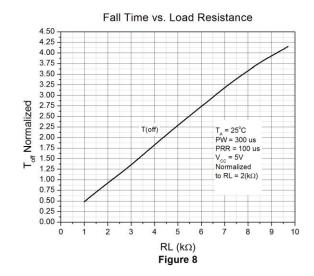


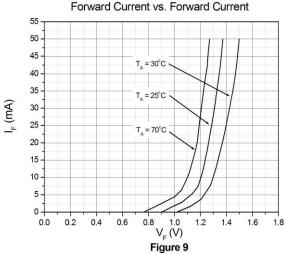




Typical Characteristic Curves

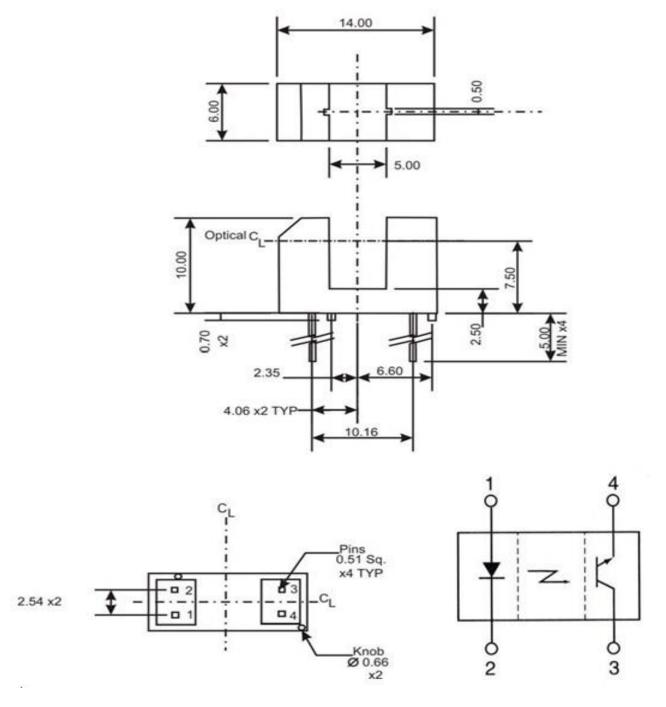








Package Dimension All dimensions are in mm, unless otherwise stated



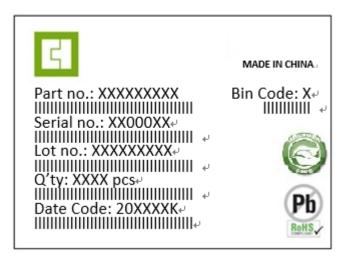
Notes:

ALL RIGHTS RESERVED.

- 1 : Dimensions for all drawings are in millimeters (inches).
- 2: Tolerance of +/- 0.25mm on all non nominal dimensions unless otherwise specified



Label Form Specification



Part no: CTM Production Number

Serial no: Production Number

Lot no: Lot number

Q'ty: Packing Quantity

Date Code: Manufacture Date

Bin Code: Ic Ranks

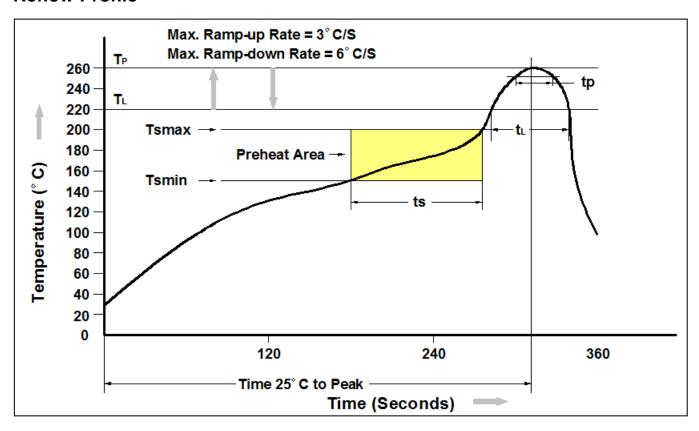
MADE IN CHINA: Production Place

Storage Condition

- 1. Do not open moisture proof bag before the products are ready to use.
- 2. The moisture barrier bag should be stored at 40°C and 90%R.H. max. before opening. Shelf life of non-opened bag is 12 months after the bag sealing date.
- 3. After opening the moisture barrier bag floor life is 72h at 30°C/60%RH. max. Unused LEDs should be resealed into moisture barrier bag. (Refer to J-STD-020 Standard)
- 4. If the moisture absorbent material has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the J-STD-033 Standard conditions.



Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t⊳)	3°C/second max.
Liquidous Temperature (T∟)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.





DISCLAIMER

CT MICRO RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. CT MICRO DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

CT MICRO ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT EXPRESS WRITTEN APPROVAL OF CT MICRO INTERNATIONAL CORPORATION.

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instruction for use provided in the labelling, can be reasonably expected to result in significant injury to the user.
- A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.